

Claim Amendments

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Claim 1 (currently-amended). A carrier and a chip configuration, comprising:

a carrier having a metal area essentially substantially composed of copper;

a chip having a rear side metallization layer;

a buffer layer configured on said metal area, said buffer layer being essentially substantially composed of nickel and having a thickness between 5 μm and 10 μm ; and

a connecting medium for fixedly connecting said chip to said carrier;

said chip being configured, without a chip housing, on said metal area such that only said connecting medium is configured between said rear side metallization layer of said chip and said buffer layer.

Claim 2 (original). The carrier and the chip configuration according to claim 1, wherein said buffer layer has a thickness between 7 μm and 9 μm .

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Claim 3 (currently-amended). The carrier and the chip configuration according to claim 2, wherein said rear side metallization layer is essentially substantially composed of aluminum.

Claim 4 (currently-amended). The carrier and the chip configuration according to claim 1, wherein said rear side metallization layer is essentially substantially composed of aluminum.

Claim 5 (currently-amended). The carrier and the chip configuration according to claim 1, wherein said buffer layer has a surface facing said chip, and said surface facing said chip includes a protective layer that is essentially substantially composed of gold.

Claim 6 (currently-amended). The carrier and the chip configuration according to claim 1, wherein said carrier is essentially substantially composed of copper.

Claim 7 (previously-amended). The carrier and the chip configuration according to claim 1, wherein said carrier includes a plate made of ceramic, said metal area is applied above said plate, and said metal area forms a contact area for said chip.